



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE7278-2E V50		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000970270						
<b>Package</b>		PG-SSOP-14-2		<b>Weight*</b>		83.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	2.83	2.83	28338	28338
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8267	
wire	non noble metal	copper	7440-50-8	27.978	33.57	34.45	335682	344465
	noble metal	gold	7440-57-5	0.171	0.20	0.20	2046	2046
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1176
plastics	plastics	epoxy resin	-	4.510	5.41		54118	
		silicondioxide	60676-86-0	44.418	53.30	58.83	532942	588236
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11712	11712
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9210	9210
glue	plastics	epoxy resin	-	0.333	0.40		3998	
		noble metal	silver	7440-22-4	1.000	1.20	1.60	11995
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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